

SUBSTRATE SUPPORT AND PLASMA PROCESSING APPARATUS

ABSTRACT

Provided are a substrate support and a plasma processing apparatus for placing an edge ring on an electrostatic chuck with high positional accuracy. A substrate support includes: a base; a first electrostatic chuck region disposed at an upper portion of the base, the first electrostatic chuck region having a substrate support surface, and being configured to hold a substrate on the substrate support surface; and a second electrostatic chuck region disposed at the upper portion of the base to surround the first electrostatic chuck region, the second electrostatic chuck region having a ring support surface, and being configured to hold an edge ring on the ring support surface. The second electrostatic chuck region is provided with a positioning pin of the edge ring, the positioning pin being formed of a material having a linear expansion coefficient substantially equal to a linear expansion coefficient of a material forming the second electrostatic chuck region.

Figure 2